MSRD620CTG

SWITCHMODE Soft Ultrafast Recovery Power Rectifier

Plastic DPAK Package

State-of-the-art geometry features epitaxial construction with glass passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies, free wheeling diode and polarity protection diodes.

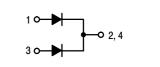
Features

- Soft Ultrafast Recovery (35 ns typ)
- Highly Stable Oxide Passivated Junction
- Matched Dual Die Construction May Be Paralleled for High Current Output
- Short Heat Sink Tab Manufactured Not Sheared
- Epoxy Meets UL 94 V-0 @ 0.125 in.
- These Devices are Pb-Free and are RoHS Compliant

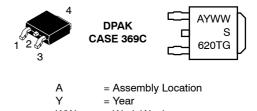
Mechanical Characteristics

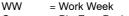
- Case: Epoxy, Molded
- Weight: 0.4 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds











G

= Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
MSRD620CTG	DPAK (Pb-Free)	75 Units/Rail
MSRD620CTT4G	DPAK (Pb–Free)	2500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating		Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _{RWM} V _R	200	V
Average Rectified Forward Current (At Rated V_R , T_C = 137°C)	Per Leg Per Package	Ι _Ο	3.0 6.0	A
Peak Repetitive Forward Current (At Rated V _R , Square Wave, 20 kHz, T _C = 138°C)	Per Leg	I _{FRM}	6.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions, Halfwave, Sing	Per Package gle Phase, 60 Hz)	I _{FSM}	50	A
Storage / Operating Case Temperature		T _{stg,} T _c	-55 to +175	°C
Operating Junction Temperature		TJ	-55 to +175	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Rating		Symbol	Value	Unit
Thermal Resistance – Junction-to-Case	Per Leg	$R_{\theta JC}$	9.0	°C/W
Thermal Resistance – Junction-to-Ambient	Per Leg	R_{\thetaJA}	80	°C/W

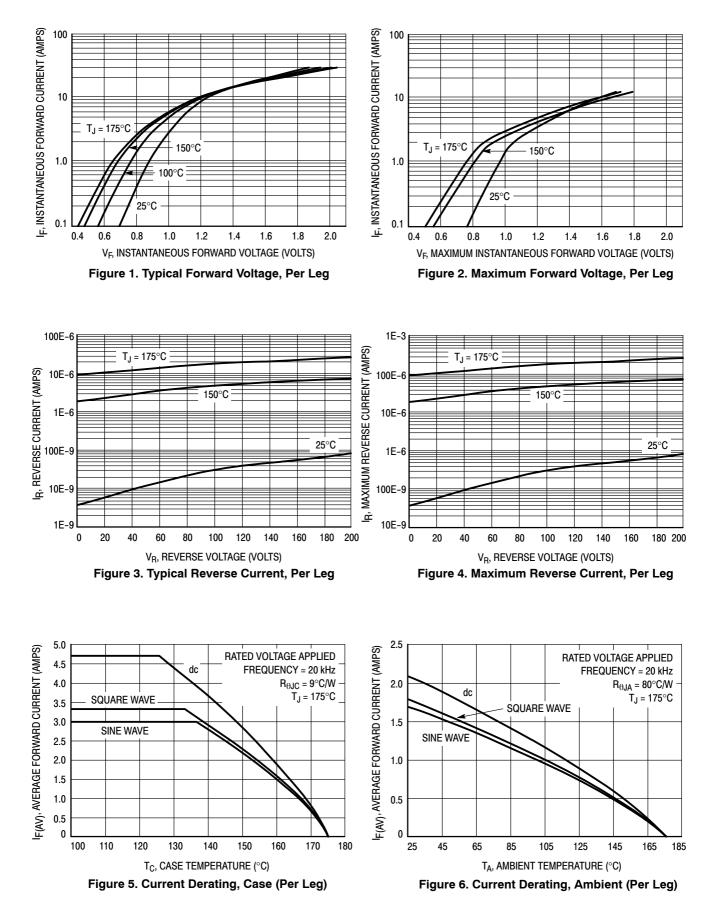
ELECTRICAL CHARACTERISTICS

Rating			Symbol	Value		Unit
Maximum Instantaneous Forward Voltage (Note 1) (See Figure 2) Per Leg		V _F	T _J = 25°C	T _J = 150°C	V	
		(I _F = 3.0 A)		1.15	1.05	
		(I _F = 6.0 A)		1.35	1.30	
Maximum Instantaneous Reverse Current (Se	e Figure 4)	Per Leg	I _R	T _J = 25°C	T _J = 150°C	μΑ
		(V _R = 200 V)		5.0	200	
		(V _R = 100 V)		2.0	100	
Maximum Reverse Recovery Time (Note 2)		Per Leg	t _{rr}			ns
	(V _R = 30 V, I _F = 1.	0 A, di/dt = 50 A/µs)			5	
	(V _R = 30 V, I _F = 3.	0 A, di/dt = 50 A/µs)		55		
Maximum Peak Reverse Recovery Current		Per Leg	I _{RM}			Α
(V _R = 30 V, I _F = 1.0 A, di/dt = 50				2.0		
	(V _R = 30 V, I _F = 3.	0 A, di/dt = 50 A/µs)		3	.0	

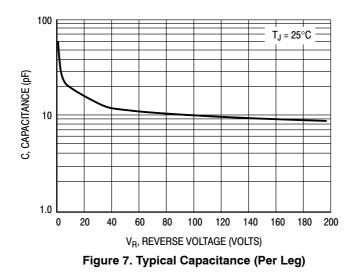
1. Pulse Test: Pulse Width \leq 250 $\mu s,$ Duty Cycle \leq 2%.

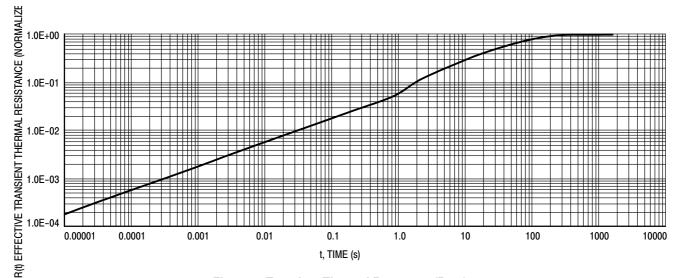
2. t_{rr} measured projecting from 25% of I_{RM} to ground.

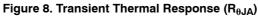
MSRD620CTG

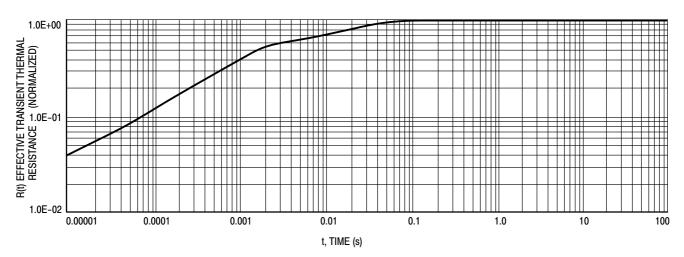


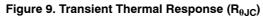
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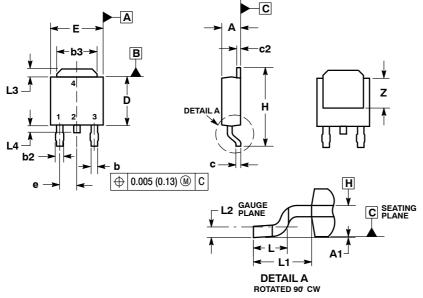




PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)

CASE 369C-01 ISSUE D

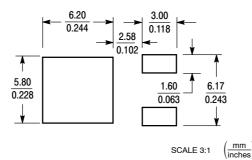


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994
- CONTROLLING DIMENSION: INCHES.
 THERMAL PAD CONTOUR OPTIONAL WITHIN DI-MENSIONS b3, L3 and Z. 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD
- FLASH, PROTRUSIONS, OR BURRS, MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL
- NOT EXCEED 0.006 INCHES PER SIDE. 5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.030	0.045	0.76	1.14	
b3	0.180	0.215	4.57	5.46	
с	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
E	0.250	0.265	6.35	6.73	
е	0.090	0.090 BSC		2.29 BSC	
н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.108	REF	2.74 REF		
L2	0.020	BSC	0.51 BSC		
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Z	0.155		3.93		

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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